









CEP20N65SA

650V ▲ 150mΩ ▲ 20A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
TO220-3L package

Super high dense cell density for extremely low R_{DS(ON)} **High power and current handling capability**

MAXIMUM RATINGS

Parameter (T _C = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	650V
Gate-Source Voltage	V _{GS}	±30V
Continuous Drain Current at T _C = 25°C	I _D	20A
Continuous Drain Current at T _C = 100°C	I _D	13A
Pulsed Drain Current Note 1	I _{DM} Note 5	80A
Maximum Power Dissipation at T _C = 25°C	P _D	205W
Power Dissipation Derating above 25°C	ΔP_D	1.64W/°C
Single Pulsed Avalanche Energy Note 6	E _{AS}	607.5mJ
Single Pulsed Avalanche Current Note 6	l _{AS}	4.5A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

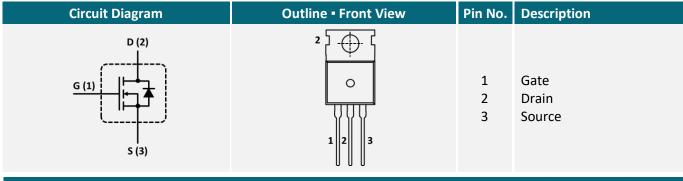
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	0.61°C/W
Thermal Resistance, Junction-to-Ambient	R _{TH JA}	62.5°C/W

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
₹			PFC	*		

PIN DESCRIPTION





ELECTRICAL CHARACTERISTICS ▲ T_C = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_{D} = 250\mu A$	BV_{DSS}	650			V
Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V$, $V_{DS} = 0V$	I_{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V$, $I_D = 20A$	R _{DS(ON)}		150	180	mΩ
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		1570		pF
Output Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		95		pF
Reverse Transfer Capacitance	$V_{DS} = 150V$, $V_{GS} = 0V$, $f = 1MHz$	C_{RSS}		15		pF
Switching Characteristics Note 3						
Turn-On Delay Time	$V_{DD} = 520V$, $V_{GS} = 10V$, $I_D = 10A$, $R_{G(ext)} = 6\Omega$	t _{D(ON)}		29		ns
Turn-On Rise Time	V_{DD} = 520V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 6Ω	t_R		10		ns
Turn-Off Delay Time	$V_{DD} = 520V$, $V_{GS} = 10V$, $I_D = 10A$, $R_{G(ext)} = 6\Omega$	t _{D(OFF)}		76		ns
Turn-Off Fall Time	V_{DD} = 520V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 6Ω	t _F		8		ns
Total Gate Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{G}		42		nC
Gate Source Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GS}		7		nC
Gate Drain Charge	$V_{DS} = 520V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GD}		15		nC
Drain-Source Diode Characteristics a	nd Maximum Ratings					
Drain-Source Diode		I _S			20	Α
Forward Current		J				
Drain-Source Diode Forward Voltage Note 2	$V_{GS} = 0V$, $I_S = 20A$	V_{SD}			1.2	V
Reverse Recovery Time	$I_D = 20A$, di/dt = $100A/\mu s$	t_{RR}		257		ns
Reverse Recovery Charge	$I_D = 20A$, di/dt = 100A/ μ s	Q_{RR}		3.04		μC
Peak Reverse Recovery Current	$I_D = 20A$, di/dt = 100A/ μ s	I_{RR}		22		Α
Max. Diode Commutation Speed	$V_{DS} = 0400V$, $V_{GS} < 20A$, $T_J = 25$ °C	dI₅/dt			1100	A/μs
Reverse Diode dV/dt ruggedness, $V_{DS} = 0480V$, $I_{SD} < I_{D}$	I_{DR} = 10A, V_{GS} = 0V, V_{DD} = 400V	dV/dt			50	V/ns
MOSFET dV/dt ruggedness, $V_{DS} = 0480V$	$I_{DR} = 10A$, $V_{GS} = 0V$, $V_{DD} = 400V$	dV/dt			160	V/ns

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Limited only by maximum temperature allowed.
- 5: Pulse width limited by safe operating area.
- 6: L = 60mH, I_{AS} = 4.5A, V_{DD} = 50V, R_{G} = 25Ω, Starting T_{J} = 25°C



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE



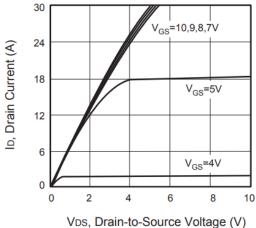


Fig. 2 • Transfer Characteristics

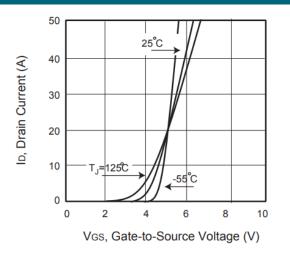


Fig. 3 • Capacitance

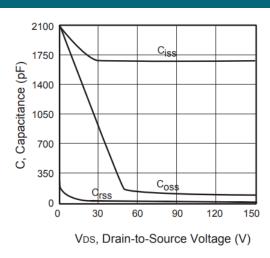


Fig. 4 • On-Resistance Variation with Temperature

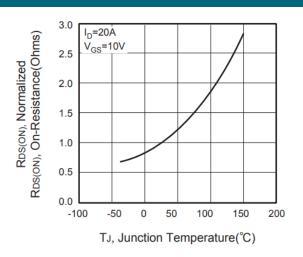


Fig. 5 • Gate Threshold Variation with Temperature

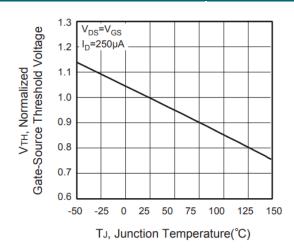
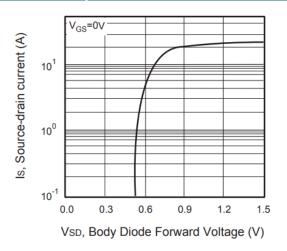


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



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Fig. 7 • Gate Charge

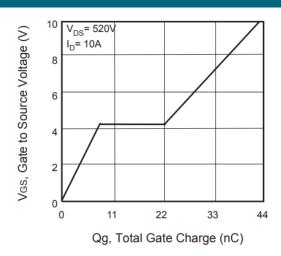


Fig. 8 • Maximum Safe Operating Area

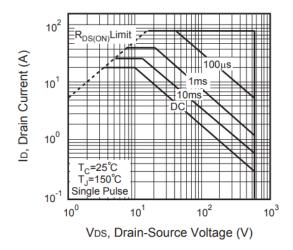
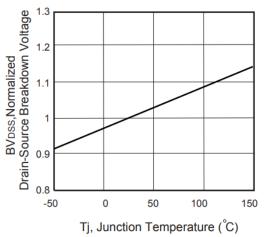


Fig. 9 • Breakdown Voltage Variation vs. Temperature





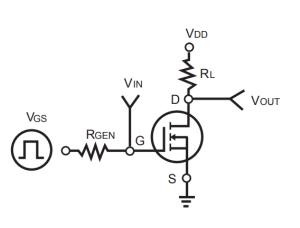
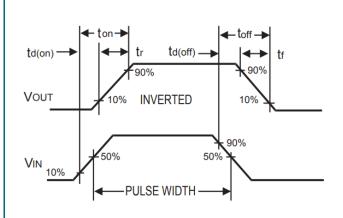


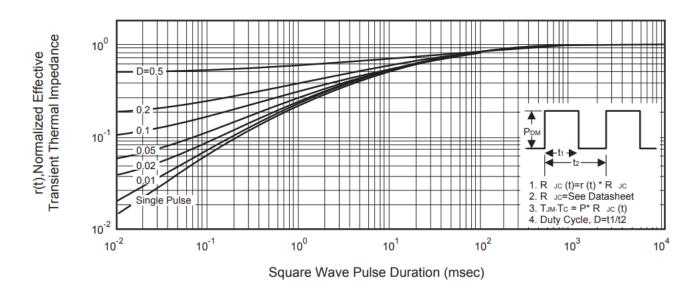
Fig. 11 • Switching Waveforms





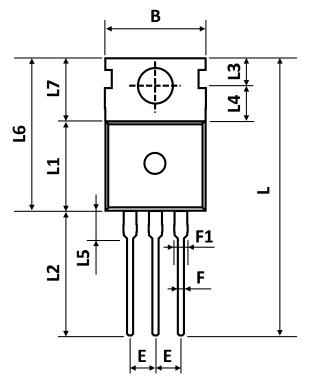
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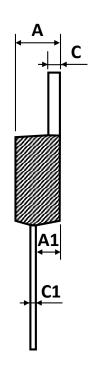
Fig. 12 • Normalized Thermal Transient Impedance Curve

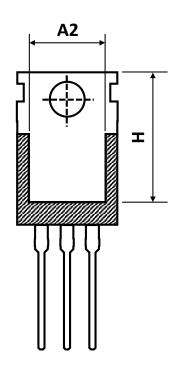




PACKAGE OUTLINE







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

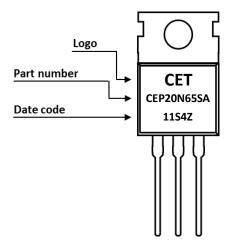
ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP20N65SA	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs

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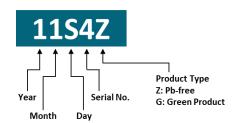


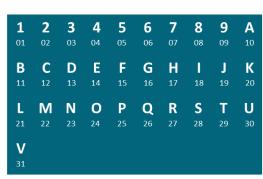
PART MARKING



DATE CODE

Example: 11S4Z



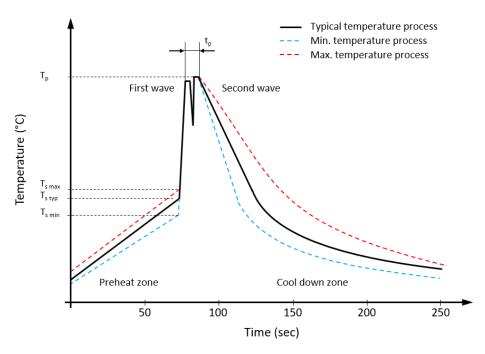


Coding list for "Day"





RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	T_{smin}	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T_{smax}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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